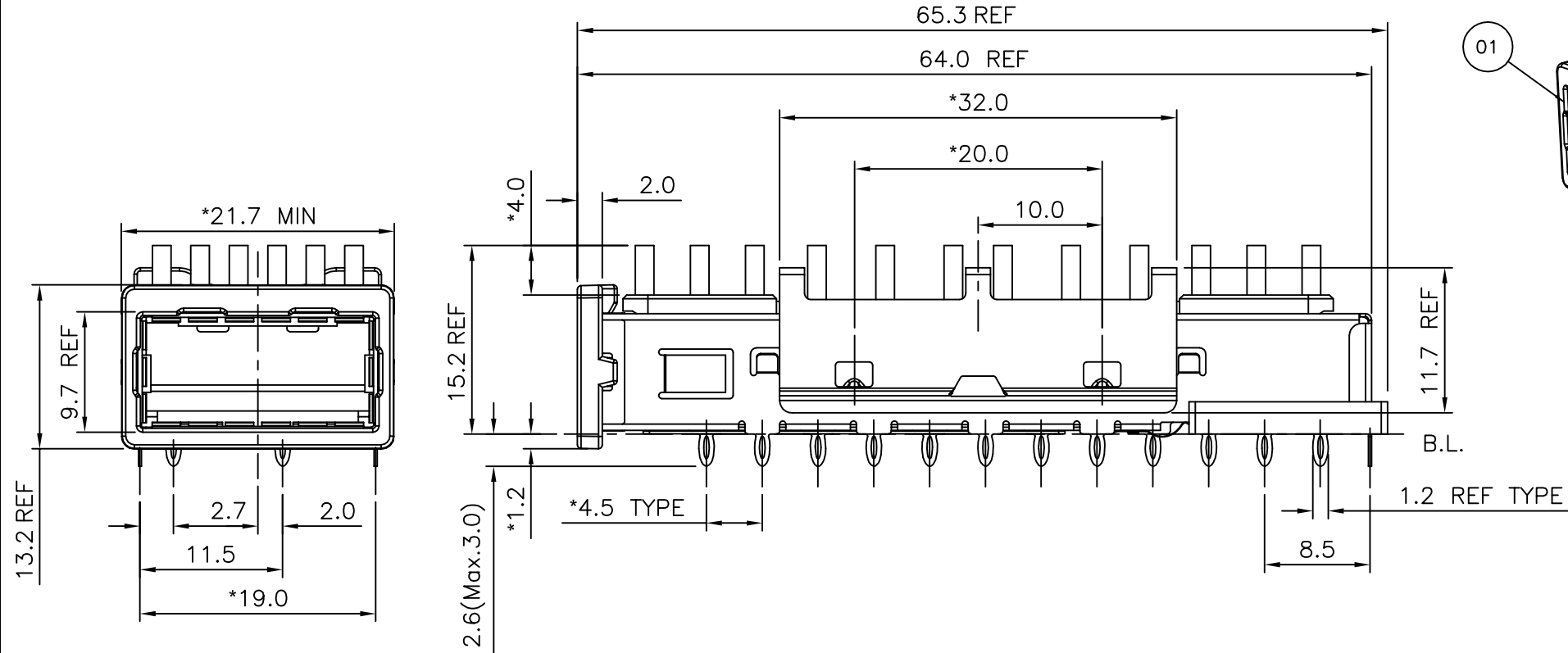
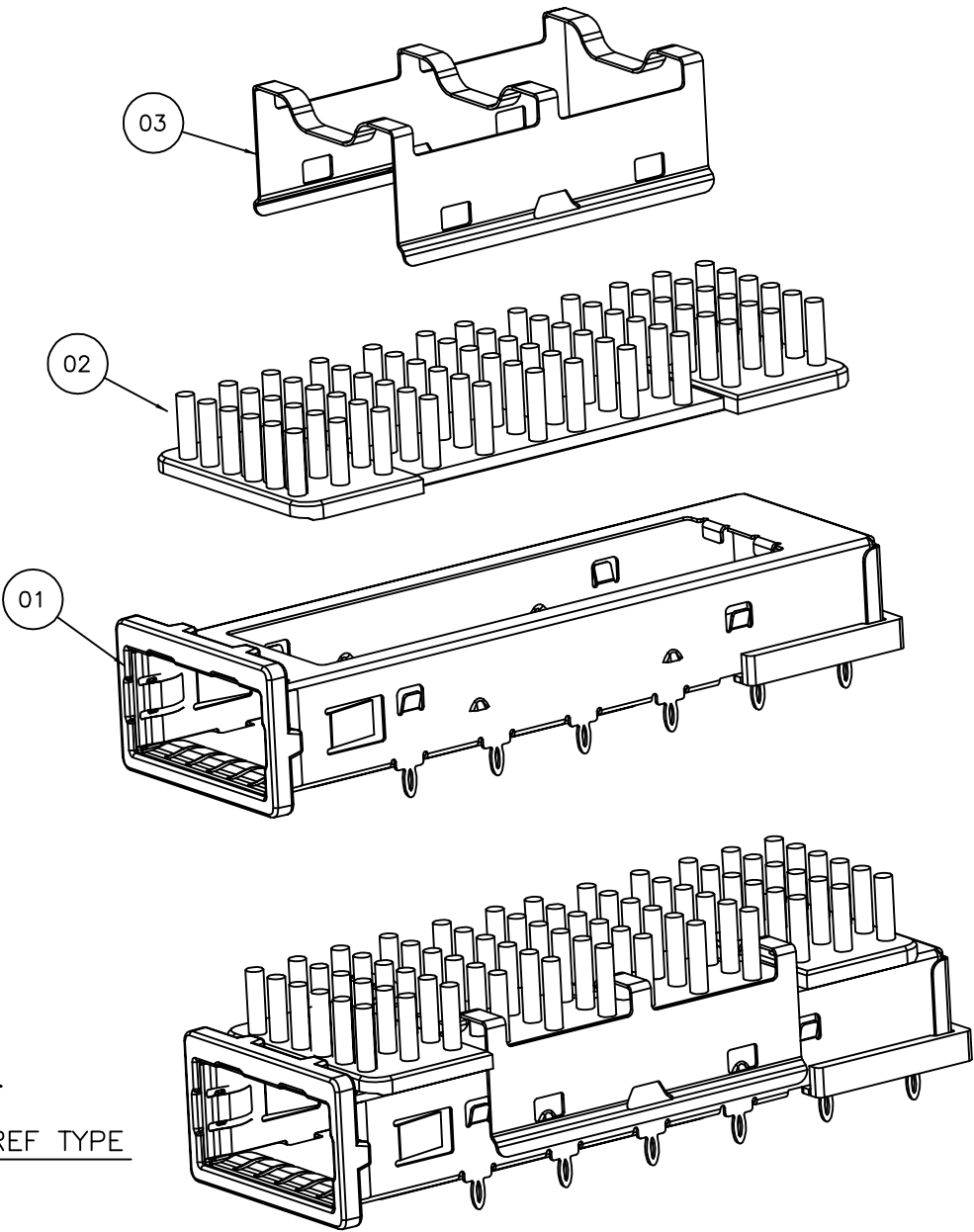
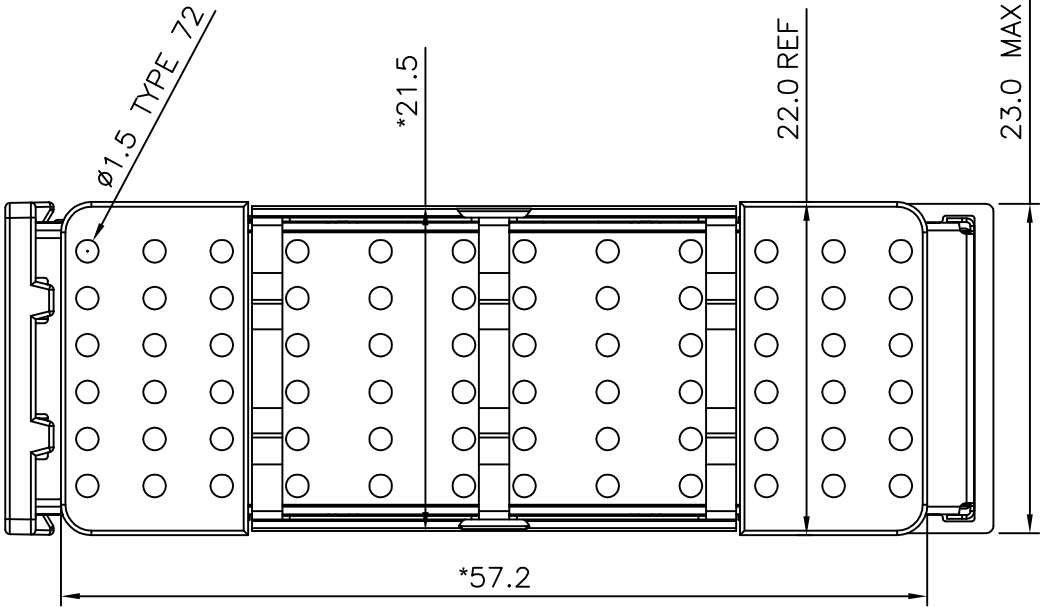


A1RFRD10

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD

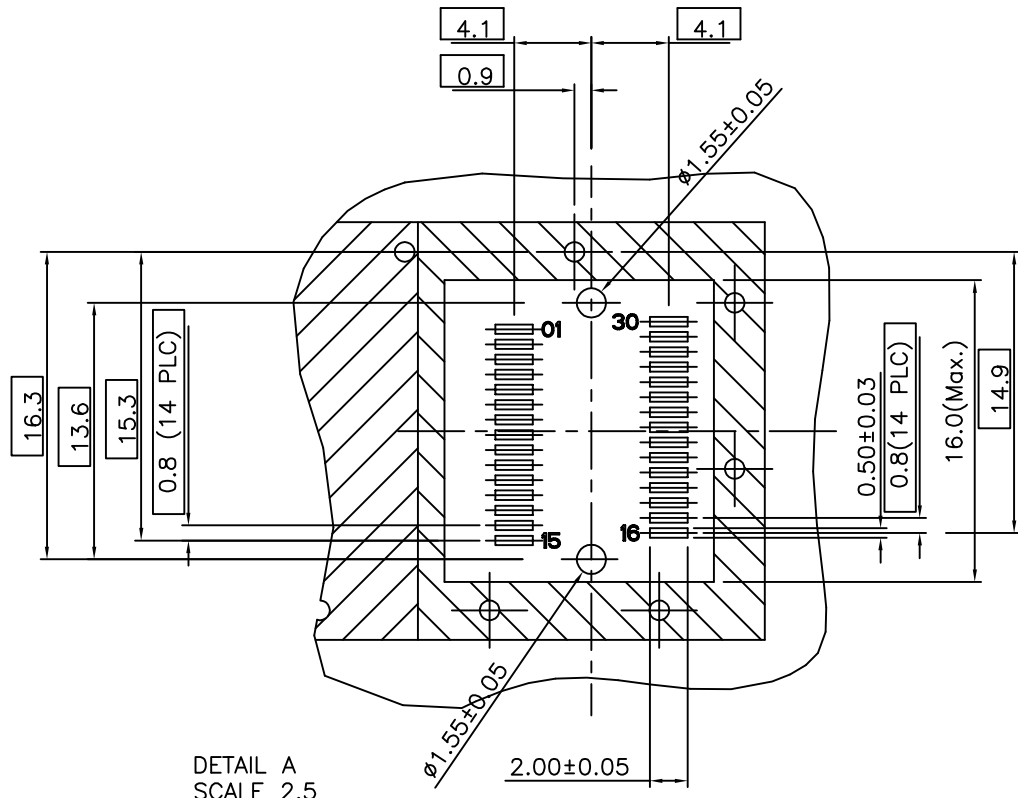
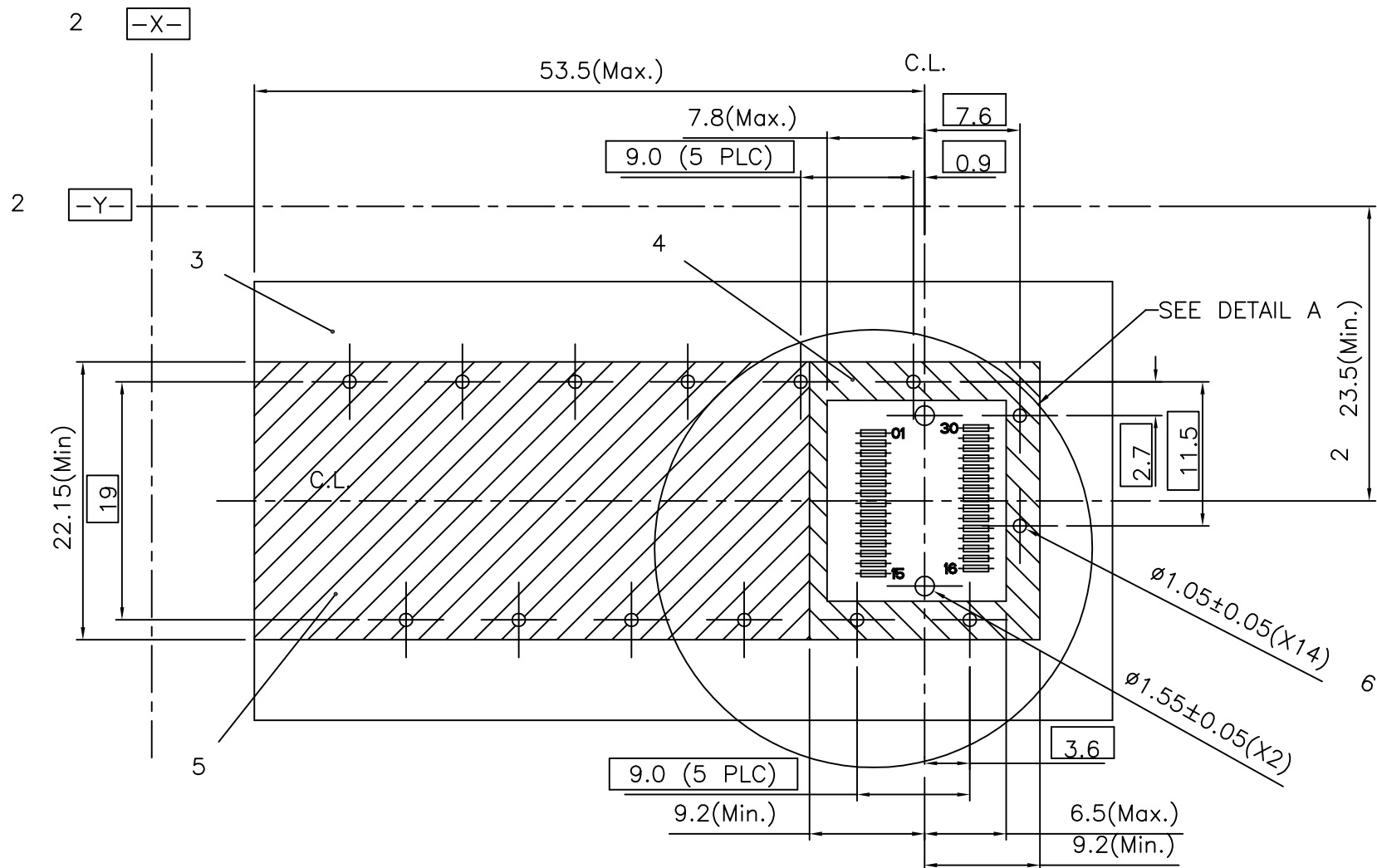


PART NUMBER: XFP002-L

No.	DESCRIPTION	Q'ty	MATERIAL	PLATING	REMARK
01	XFP CAGE ASSEMBLY (Non-Logo)	1			
02	XFP HEAT SINK (4.00mm)	1	AL	Ni	
03	XFP HEAT SINK CLIP	1	SUS		

DETACHED LISTS	MM (INCH)		DFTO tzou	DATE 06/02/06'	FULL RISE ELECTRONIC CO., LTD		
	TOLERANCES EXCEPT AS NOTED		CHKD	DATE			
			MFO	DATE	TITLE (Non-Logo)		
			APPVL	DATE			
					DRAWING NO. XFPO02-L		
			MATERIAL :				
	ANGLES ± 0.5		QT'Y :		SIZE A3		
			FINISH :				
			SCALE : 1 : 2		DO NOT SCALE DRAWING		
	THIRD ANGLE PROJECTION						

REVISION RECORD				
REV	ECO	DESCRIPTION	DRFT	CHKD



RECOMMEND P.C.B. LAYOUT

Note:

- 1 DESIGN MEETS REQUIREMENTS OF XFPMSA SPECIFICATION REV. 3.1 (10 GIGABIT SMALL FROM FACTOR PLUGGABLE MODULE).

2 DATUM $\overline{X}$ AND $\overline{Y}$ ESTABLISHED BY CUSTOMER.

3 DATUM $\overline{A}$ IS TOP SURFACE OF HOST BOARD.

4 INDICATED SURFACES TO BE CONDUCTIVE AND CONNECTED TO CHASSIS GROUND.
- 5 CROSS-HATCHED AREA DENOTES COMPONENT AND TRACE KEEP-OUT (EXCEPT CHASSIS GROUND)

6 RECOMMENDATION FOR P.C.BOARD HOLES:
A. HOLE ϕ AFTER DRILLING : 1.15 ± 0.02 mm.
B. HOLE ϕ Sn PLATE : 1.05 ± 0.05 mm.
C. 25 μ m ~ 50 μ m COPPER UNDERPLATE.

7 -CAUTION- REFLOW PROCESS WILL DAMAGE CAGE ASSEMBLY.

DETACHED LISTS	MM (INCH)	DFTO tzou	DATE 06/02/06'	FULL RISE ELECTRONIC CO., LTD		
	TOLERANCES EXCEPT AS NOTED	CHKD	DATE			
	MM	MFO	DATE	TITLE (Non-Logo) XFP CAGE WITH PCI HEAT SINK KIT		
	.0 $\pm$ 0.2 $\pm$	APPL	DATE			
	.00 $\pm$ 0.15 $\pm$	MATERIAL :		DRAWING NO. XFP002-L		
ANGLES $\pm$ 0.5		QT'Y :		/PART NO. SEE NOTE		SIZE A3
THIRD ANGLE PROJECTION		FINISH :		DO NOT SCALE DRAWING		REV 0
		SCALE : 1 : 2		SHEET 2 OF 2		